

# 30.48mm(1.2 INCH) 16 SEGMENT SINGLE DIGIT ALPHANUMERIC NUMERIC DISPLAY

Part Number: PSC12-11CGKWA Green

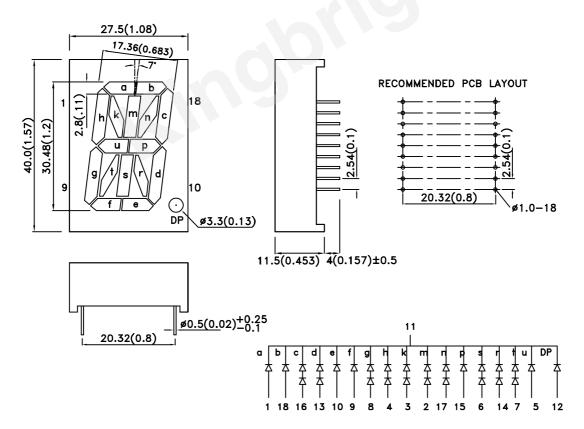
#### **Features**

- 1.2 inch character height .
- Low current operation.
- High contrast and light output.
- Easy mounting on P.C. boards or sockets.
- Categorized for luminous intensity.
- Mechanically rugged.
- Standard:gray face, white segment.
- RoHS compliant.

### **Description**

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

# Package Dimensions& Internal Circuit Diagram







#### Notes

- 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
- 2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAK2863 REV NO: V.5A DATE: MAY/10/2013 PAGE: 1 OF 7

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: F.Cui ERP: 1311000358

### **Selection Guide**

Part No.	Dice	Lens Type	lv (ucd) [1] @ 10mA		Description
			Min.	Тур.	-
PSC12-11CGKWA	Green (AlGalnP)	White Diffused	14000	25000	Common Cathode, Rt. Hand Decimal.
			*3600	*9000	

# Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter		Device	Тур.	Max.	Units	Test Conditions
λ peak	Peak Wavelength		Green	574		nm	IF=20mA
λ D[1]	Dominant Wavelength		Green	570		nm	IF=20mA
Δλ 1/2	Spectral Line Half-width		Green	20		nm	IF=20mA
С	Capacitance		Green	15		pF	VF=0V;f=1MHz
VF[2] Forward Voltage	c,d,g,h,k,m,n,s,r,t	Green	4.2	5	V	IF=20mA	
	Voltage	a,b,e,f,p,u and DP	Green	2.1	2.5	V	IF=20MA
IR Currer	Reverse	c,d,g,h,k,m,n,s,r,t	Green		10	uA	VR = 5V
	(Per Chip)	a,b,e,f,p,u and DP			10	uA	

### Notes:

# Absolute Maximum Ratings at TA=25°C

Parameter		Green	Units	
Dower discination	c,d,g,h,k,m,n,s,r,t	150		
Power dissipation	a,b,e,f,p,u and DP	(75)	mW	
DC Forward Current	c,d,g,h,k,m,n,s,r,t 30	30	A	
DC Forward Current	a,b,e,f,p,u and DP	(30)	mA	
Peak Forward Current [1]	c,d,g,h,k,m,n,s,r,t	150	mA	
Peak Forward Current [1]	a,b,e,f,p,u and DP	(150)	IIIA	
Reverse Voltage (Per Chip)	c,d,g,h,k,m,n,s,r,t	5	V	
	a,b,e,f,p,u and DP	5	V	
Operating / Storage Temperature		-40°C To +85°C		
Lead Solder Temperature[2]		260°C For 3-5 Seconds		

# Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.

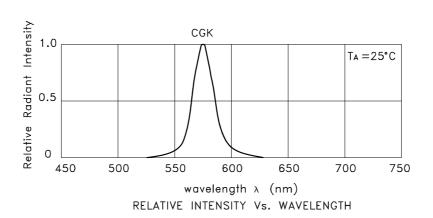
SPEC NO: DSAK2863 **REV NO: V.5A** DATE: MAY/10/2013 PAGE: 2 OF 7 APPROVED: WYNEC **CHECKED:** Joe Lee DRAWN: F.Cui ERP: 1311000358

<sup>1.</sup> Luminous intensity/ luminous Flux: +/-15%.

\* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

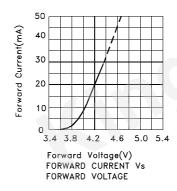
<sup>1.</sup>Wavelength: +/-1nm. 2.Forward Voltage: +/-0.1V.

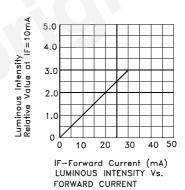
<sup>3.</sup> Wavelength value is traceable to the CIE127-2007 compliant national standards.

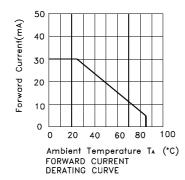


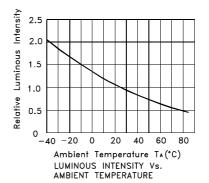
# Green

# PSC12-11CGKWA



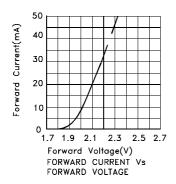


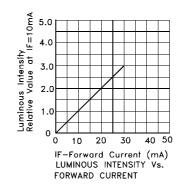


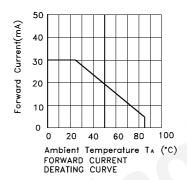


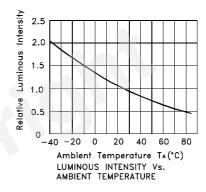
Note: the curves are on the segment c,d,g,h,k,m,n,s,r and t.

SPEC NO: DSAK2863 APPROVED: WYNEC REV NO: V.5A CHECKED: Joe Lee DATE: MAY/10/2013 DRAWN: F.Cui PAGE: 3 OF 7 ERP: 1311000358



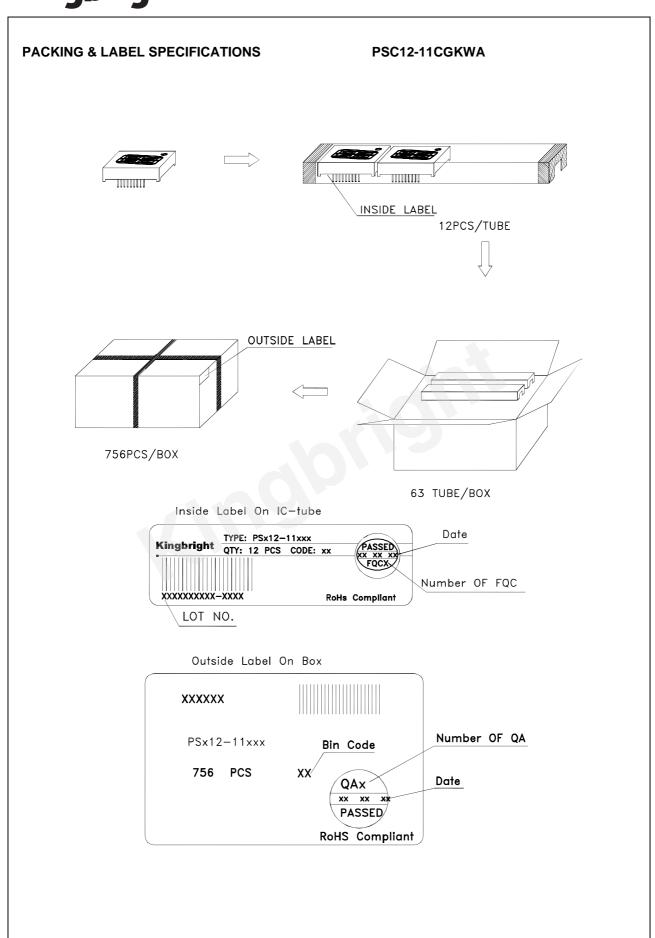






Note: the curves are on the segment a,b,e,f,p,u and DP.

SPEC NO: DSAK2863 APPROVED: WYNEC REV NO: V.5A CHECKED: Joe Lee DATE: MAY/10/2013 DRAWN: F.Cui PAGE: 4 OF 7 ERP: 1311000358

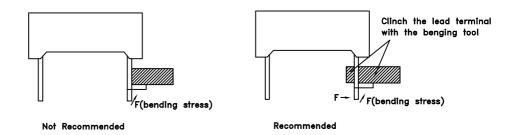


SPEC NO: DSAK2863 APPROVED: WYNEC REV NO: V.5A CHECKED: Joe Lee DATE: MAY/10/2013 DRAWN: F.Cui PAGE: 5 OF 7 ERP: 1311000358

# THROUGH HOLE DISPLAY MOUNTING METHOD

# Lead Forming

Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

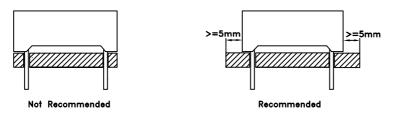


### Installation

- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



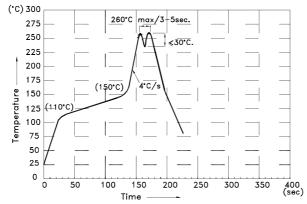
3.The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



SPEC NO: DSAK2863 APPROVED: WYNEC REV NO: V.5A CHECKED: Joe Lee DATE: MAY/10/2013 DRAWN: F.Cui PAGE: 6 OF 7 ERP: 1311000358

### DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



#### NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top-surface temperature should be kept below 105°C
- 5.No more than once.

# Soldering General Notes:

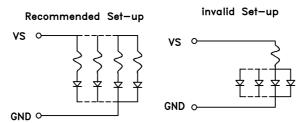
- 1. Through—hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

### **CLEANING**

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

### CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



Detailed application notes are listed on our website. http://www.kingbright.com/application\_notes

SPEC NO: DSAK2863 REV NO: V.5A DATE: MAY/10/2013 PAGE: 7 OF 7

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: F.Cui ERP: 1311000358